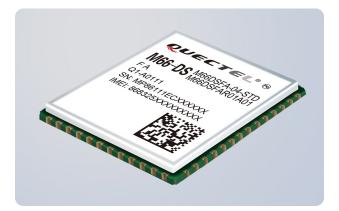


# **Quectel M66-DS**

Ultra-small Dual SIM Dual Standby Quad-band GSM/GPRS Module



M66-DS is an ultra-small Dual SIM Dual Standby quad-band GSM/GRPS module using LCC castellation package. Based on the latest 2G chipset, it has the optimal performance in SMS & data transmission and audio service even in harsh environment. The Dual SIM Dual Standby function allows customers to use two (U)SIM cards in one device simultaneously. The ultra-compact 15.8mm × 17.7mm × 2.3mm profile makes M66-DS a perfect platform for size sensitive applications.

M66-DS adopts surface mount technology, making it an ideal solution for durable and rugged designs. The low profile and small size of LCC package ensures M66-DS can be easily embedded into low-volume applications and provides reliable connectivity for the applications. This kind of package is ideally suited for large-scale manufacturing which has strict requirements for cost and efficiency.

The compact form factor, low power consumption and two (U)SIM card interfaces make M66-DS the best choice for applications such as wearable device, automotive, industrial PDA, personal tracking, wireless POS, smart metering, telematics and other M2M applications.



 Embedded powerful Internet service protocols, multiple Sockets & IP addresses

DSDS

Digital Audio B

Bluetooth 3.0

# **Quectel M66-DS**

Ultra-small Dual SIM Dual Standby Quad-band GSM/GPRS Module



Quad-band: 850/ 900/ 1800/ 1900MHz

#### Data

GPRS Class 12: Max. 85.6kbps (Downlink) Max. 85.6kbps (Uplink) PBCCH Coding Schemes: CS 1, 2, 3. 4 USSD Non-transparent Mode

#### SMS

Point-to-point MO and MT SMS Cell Broadcast Text and PDU Mode

### Voice

Speech Codec Modes: Half Rate (HR) Full Rate (FR) Enhanced Full Rate (EFR) Adaptive Multi-Rate (AMR) Echo Arithmetic: Echo Cancellation Echo Suppression Noise Reduction

### Interfaces

(U)SIM Card Interface: × 2 (3.0V/ 1.8V) UART × 3

#### Analog Audio Channel:

2 Output Channels and 1 Input Channel Bluetooth: BT 3.0 Profile: SPP, HFP ADC\* × 1 PCM\* × 1 SD\* × 1 RTC × 1 Antenna Pad:

× 2 (GSM Antenna Pad and Bluetooth Antenna Pad)

### **Enhanced Features**

DSDS eCall Jamming Detection DTMF Audio Play/ Audio Record QuecFOTA<sup>™</sup> QuecCell QuecCell QuecLocator QuecFile OpenCPU<sup>™</sup> RIL for Android MUX Bluetooth

#### **Electrical & Sensitivity**

Output Power: Class 4 (2W @850/ 900MHz) Class 1 (1W @1800/ 1900MHz) Consumption: 1.3mA @DRX=5 1.2mA @DRX=9

#### Sensitivity:

*QUECTEL*° ®

M66-DS M66DSFA-04-STD F A Q1-A0111 SN: MP86111ECXXXXX IMEI: 868325XXXXXXXX

15.8 mm

**8**68

12

17.7 mm

GSM850: -109dBm GSM900: -109dBm DCS1800: -109dBm PCS1900: -109dBm Supply Voltage: 3.3V~4.6V, 4.0V Typ.

2.3 mn

#### Software Features

BT 3.0 Protocols: TCP/ UDP/ PPP/ FTP/ HTTP/ SMTP\*/ CMUX/ DSDS

### **General Features**

GPRS Multi-slot Class: Class 12 GPRS Mobile Station: Class B Temperature Range: -40°C ~ +85°C Dimensions: 17.7mm × 15.8mm × 2.3mm LCC Package Weight: Approx. 1.3g GSM 07.07, 07.05 and other Enhanced AT Commands

\* Under Development

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